



## Material Content Data Sheet



<b>Sales Product Name</b>		BSZ900N20NS3 G		<b>Issued</b>		22. July 2019		
<b>MA#</b>		MA004242856						
<b>Package</b>		PG-TSDSON-8-38		<b>Weight*</b>		36.10 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.909	2.52	2.52	25179	25179
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		98	
	non noble metal	zinc	7440-66-6	0.014	0.04		392	
	non noble metal	iron	7439-89-6	0.283	0.78		7848	
wire	non noble metal	copper	7440-50-8	11.505	31.87	32.70	318659	326997
	noble metal	gold	7440-57-5	0.028	0.08	0.08	764	764
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1029
plastics	plastics	epoxy resin	-	1.913	5.30		52974	
	inorganic material	silicondioxide	60676-86-0	16.619	46.04	51.44	460311	514314
	leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10250
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2238	2238
solder	non noble metal	tin	7440-31-5	0.022	0.06		596	
	noble metal	silver	7440-22-4	0.027	0.07		746	
	non noble metal	lead	7439-92-1	1.028	2.85	2.98	28482	29824
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		109	
	non noble metal	iron	7439-89-6	0.078	0.22		2170	
	non noble metal	copper	7440-50-8	3.182	8.81	9.04	88128	90434
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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